

ABSTRACT

According to the present invention, mask film (2a), where squeegee cleaning part (6) has been formed at a predetermined position, and mask film (2b) are attached to both sides of a substrate. Through-hole (3) is formed by
5 using a laser, and conductive paste (4) is filled into through-hole (3) by using a squeezing method. As discussed above, a paste-residue can be prevented on through-hole (3), so that a circuit board having high quality of connection can be obtained.